

In re Patent Application of:
AMMAR ET AL.
Serial No. **Not Yet Assigned**
Filed: **Herewith**

In the Claims:

Please cancel Claims 1-20.

Please add new Claims 21-40 as follows:

21. A method for transferring radio frequency (RF) signals between first and second cooperating circuit boards comprising the steps of:

positioning a housing member having a connector with opposing ends against the first printed circuit board such that one end of the connector engages a circuit on the first printed circuit board;

biasing another end of the connector into connection with a circuit of a second printed circuit board; and

transferring RF signals between the boards via the connector.

22. A method according to claim 21, and further comprising the step of transferring ground signals using connectors positioned on either side of the connector that transfers RF signals.

23. A method according to claim 21, and further comprising the step of soldering the end of the connector engaging the first printed circuit board.

24. A method according to claim 21, wherein the connector is solderless on at least one end.

25. A method according to claim 21, and further comprising the step of transferring DC signals using

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connectors additional to the connector that transfers RF signals.

26. A method according to claim 21, and further comprising the step of positioning a plurality of housing members adjacent to each other and transferring ground signals using connectors positioned on either side of the connector that transfers RF signals.

27. A method according to claim 21, and further comprising the step of transferring RF signals at no less than 4 GHz.

28. A method according to claim 21, wherein the connector comprises one or more surface mount pressure contacts.

29. A method according to claim 21, and further comprising the step of mixing the RF signals with a carrier frequency.

30. A method of transferring RF signals between first and second cooperating printed circuit boards comprising :
providing a connector between two boards, without use of connecting wires between the boards; and
transferring RF signals between the boards via the connector.

31. A method according to claim 30, and further comprising the step of transferring the RF signals at no less than 4 GHz.

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32. A method according to claim 30, wherein the connector is solderless on at least one end.

33. A method according to claim 30, wherein the connector comprises one or more surface mount contacts.

34. A method according to claim 30, and further comprising the step of mixing the RF signals with a carrier frequency and/or other RF processing signals that add functionality.

35. A method according to claim 30, and further comprising the step of transferring ground signals using connectors positioned on either side of the connector that transfers RF signals.

36. A connector system for transferring RF signals between first and second cooperating printed circuit boards, comprising:

a housing member having a connector with opposing ends that is positioned against the first printed circuit board such that one end of the connector engages a circuit on the first printed circuit board and another end of the connector is biased into connection with a circuit of the second printed circuit board wherein RF signals are transferred via the connector between the first and second printed circuit boards.

37. A connector system according to claim 36, wherein said RF signals are transferred at frequencies no less than 4 GHz with very low losses.

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38. A connector system according to claim 36, wherein the connector is solderless on at least one end.

39. A connector system according to claim 36, wherein the comprises one or more surface mount pressure contacts.

40. A connector system according to claim 36, wherein RF signals are mixed with a carrier frequency and/or RF processing signals.